Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	188	FIB adj etching	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/24 09:12
S2	234	opaque adj defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/18 16:15
S4	5	S1 and S2	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/18 16:39
S5	429852	mask	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/18 16:40
S6	135	S2 and S5	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/18 16:42
S7	3519970	(examin\$4 inspect\$4 measur\$4)	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/18 16:43
S8	1848366	substrate	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/18 17:36
S 9	41	reflectivity adj percentage	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/18 17:15
S10	22	S7 and S9	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/18 17:17

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S11	0	S2 and S10	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/18 17:15
S12	87847	"356".clas.	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/18 17:17
S13	6	S10 and S12	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/18 17:36
S14	0	S2 and S9	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/18 17:36
S15	2055187	substrate wafer	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/18 17:36
S16	2360982	substrate wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/18 17:36
S17	108486	S7 with S16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/18 17:36
S18	47	S17 and S2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/18 17:37
S19	47	S17 and S2	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/18 17:45

S20	208	reference adj reflectance	USPAT;	OR	OFF	2006/07/18 17:57
	200		USOCR; EPO; JPO; DERWENT; IBM_TDB		3.7	2300,07,10 17.37
S21	4018	reference with reflectance	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/19 14:30
S22	929	reference near2 reflectance	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/19 14:30
S23	3518551	compar\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/19 14:30
S24	3519970	(examin\$4 inspect\$4 measur\$4)	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/19 15:00
S25	37717	(wafer substrate) near2 mask	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/19 15:00
S26	17	S22 and S23 and S24 and S25	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/19 16:02
S27	84357	"180".clas.	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/19 16:03
S28	1107	180/65.2.ccls.	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/19 16:03

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S29	929	reference near2 reflectance	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/20 07:58
S30	3521579	compar\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/20 07:58
S31	3519970	(examin\$4 inspect\$4 measur\$4)	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/20 07:58
S32	37717	(wafer substrate) near2 mask	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/20 07:58
S33	17	S29 and S30 and S31 and S32	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/20 09:47
S34	2	("5,291,269").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/20 14:38
S35	3347	rate near2 reflection	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 14:38
S36	85944	"356".clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 14:38
S37	105	S35 and S36	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 14:39

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S38	453537	feedback	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 14:39
S39	18	S37 and S38	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 14:42
S40	2	10/254279	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 14:42
S41	3519970	(examin\$4 inspect\$4 measur\$4)	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/20 16:49
S42	443167	reticle mask	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/20 16:49
S43	6561	S41 near2 S42	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/20 16:49
S44	11	S35 and S43	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/20 16:49
S45	4291661	reference	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/20 16:49
S46	10	S44 and S45	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/20 16:49
S47	3347	rate near2 reflection	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/23 20:05

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S48	3520697	(examin\$4 inspect\$4 measur\$4)	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 20:05
S49	443348	reticle mask	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 20:05
S50	6562	S48 near2 S49	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 20:05
S51	11	S47 and S50	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 20:05
S52	4291924	reference	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 20:05
S53	10	S51 and S52	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 20:05
S54	188	FIB adj etching	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 20:45
S55	234	opaque adj defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 20:45
S56	10	S54 and S55	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 20:45
S57	3520697	(examin\$4 inspect\$4 measur\$4)	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 20:45

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S58	2363585	substrate wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 20:45
S59	108522	S57 with S58	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 20:45
S60	47	S59 and S55	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 20:48
S61	85944	"356".clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/23 20:45
S62	105	S47 and S61	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/23 20:45
S63	453603	feedback	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/23 20:45
S64	18	S62 and S63	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/23 20:45
S65	18	"5291269"	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 20:48
S66	2	"5291269".pn.	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 20:48

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S67	1	S66 and compar\$5	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 20:49
S68	0	S67 and feedback	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 20:49
S69	614750	etch\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/24 09:18
S70	446535	correlat\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/24 09:18
S71	1165676	height	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/24 09:18
S72	3616	S70 with S71	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/24 09:18
S73	5	S69 with S72	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/24 09:22
S74	20	S69 same S72	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/24 09:22
S75	15	S74 not S73	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/24 09:23
S76	188	FIB adj etching	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/24 09:38

7/24/06 1:49:48 PM

S77	234	opaque adj defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/24 09:33
S78	5	S76 and S77	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/24 09:33
S79	604	((FIB) focused adj ion adj beam) adj etching	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/24 09:38
S80	15	S79 and S77	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/24 09:38
S81	3520697	(examin\$4 inspect\$4 measur\$4)	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/24 09:43
S82	6	S81 and S80	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/24 10:03
S83	6	(US-5744381-\$ or US-6891629-\$ or US-6753538-\$ or US-6593040-\$ or US-6322935-\$).did. or (US-20050146715-\$).did.	USPAT; DERWENT	OR	ON	2006/07/24 10:02
S84	0	S83 and feeback	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/24 10:02
S85	2	S83 and feedback	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/24 10:02
S86	2	S82 and feedback	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/24 12:00

COZ	1205104	relationship	LICDATE		055	2006/07/24 12 62
S87	1295104	relationship	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/24 12:02
S88	10134782	between	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/24 12:02
S89	581237	intensity	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/24 12:02
S90	1183683	height	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/24 12:02
S91	23810	S87 and S88 and S89 and S90	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/24 12:02
S92	68	S87 with S88 with S89 with S90	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/24 12:02
S93	87847	"356".clas.	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/24 12:02
S94	21	S92 and S93	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/24 12:16
S95	2	"5,804,813".pn.	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/24 12:17